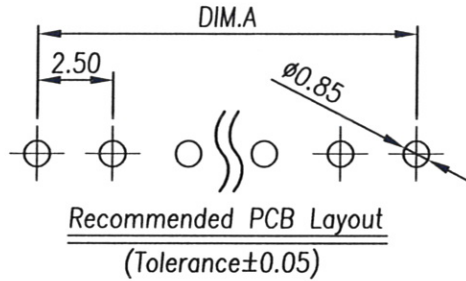
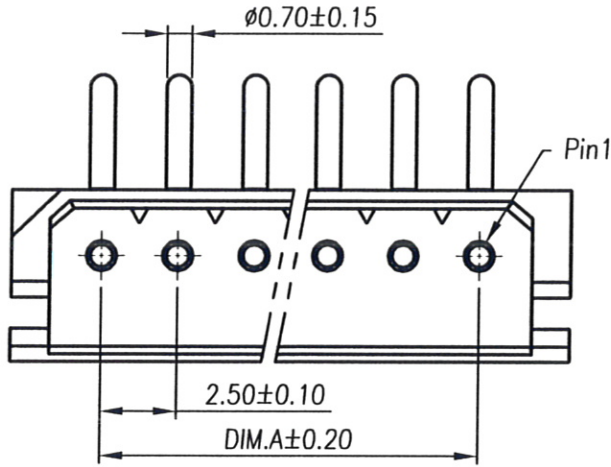




RoHS Compliant

REV	MODIFICATION	DATE	DRAW
A0	Release To ECN20110409	2011.04.19	Ivy
A1	Release To ECN20130303	2013.03.12	Seven



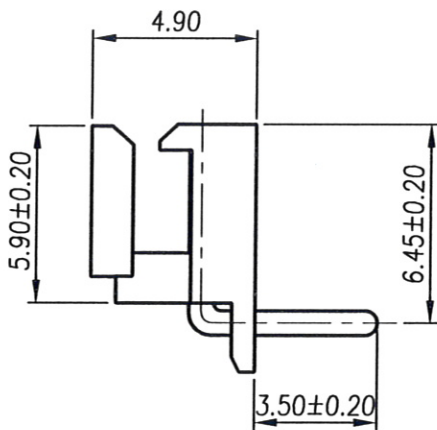
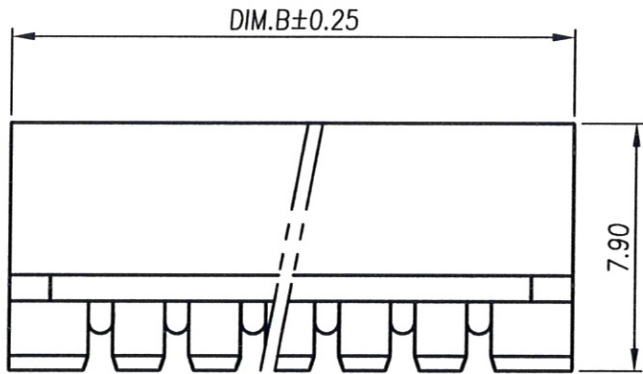
Specification  
 1.Current Rating:3A AC/DC  
 2.Voltage Rating:250V AC/DC  
 3.Contact Resistance:20m $\Omega$  Max.  
 4.Insulation Resistance:1000M $\Omega$  Min. At DC 500V  
 5.Dielectric Withstanding Voltage:1000V AC/Minute  
 6.Operating Temperature:-25 $^{\circ}$ C~+85 $^{\circ}$ C

Material:  
 1.Housing:High-Temp. Thermoplastic UL94V-0  
 2.Contact Pin:Copper Alloy  $\phi 0.70$ mm

Finish:  
 1.Housing:Natural  
 2.Contact Pin:Bright Tin Over Nickel

Part No.: AD05001 XX 1 1 5 6

Number Of Pin     ┌  
 02~16             └ Packing  
                            ┌ 5:Bag  
                            └ Plating  
 Housing Material     ┌  
 1:NY66 UL94V-0 Nature     └ 1:Bright Tin Plated Over Ni.



PIN	DIM.A	DIM.B	PIN	DIM.A	DIM.B
02	2.50	7.50	10	22.50	27.50
03	5.00	10.00	11	25.00	30.00
04	7.50	12.50	12	27.50	32.50
05	10.00	15.00	13	30.00	35.00
06	12.50	17.50	14	32.50	37.50
07	15.00	20.00	15	35.00	40.00
08	17.50	22.50	16	37.50	42.50
09	20.00	25.00			



**金上達科技股份有限公司**  
**GOLDENSUNDA TECHNOLOGY CO.,LTD**

TOLERANCE UNLESS OTHERWISE SPECIFIED

.x $\pm$ 0.35	x.* $\pm$ 2'	PROJ.	TITLE: Wire To Board Wafer 2.50mm 90° DIP
.xx $\pm$ 0.25	.x.* $\pm$ 1'	APR. Jay 20130312	PART NO. AD05001XX1156
.xxx $\pm$ 0.15	.xx.* $\pm$ 0.5'	CHK. Michelle 20130312	DWG NO. AD05001XX1156
		DRA. Seven 20130212	UNITS: mm

**CUSTOMER DRAWING**

SIZE: **A4** SCALE: 4:1 SHEET 1 / 1 REV A1 V